Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2847

DC-DC Converter and Motor Drive Applications

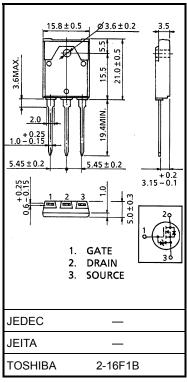
• Low drain-source ON resistance : RDS (ON) = 1.1 Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720 V)$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	900	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	900	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	8	Α
	Pulse (Note 1)	I _{DP}	24	А
Drain power dissipation	n (Tc = 25°C)	PD	85	W
Single pulse avalanch	e energy (Note 2)	E _{AS}	799	mJ
Avalanche current		I _{AR}	8	Α
Repetitive avalanche	energy (Note 3)	E _{AR}	8.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature r	ange	T _{stg}	-55~150	°C



Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.47	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	41.6	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 22.9 mH, R_{G} = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

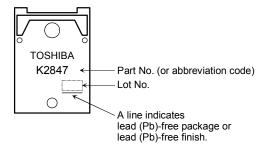
Electrical Characteristics (Ta = 25°C)

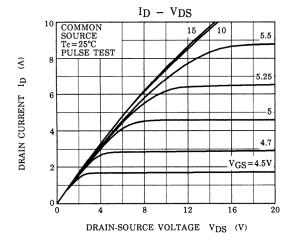
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		_	±10	μΑ
Gate-source br	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V		_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A	_	1.1	1.4	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.0	7.0	_	S
Input capacitano	ce	C _{iss}			2040	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		45	_	
Output capacitance		Coss			190	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{\underset{0V}{\bigvee}} \stackrel{I_{D}=4A}{\underset{VOUT}{\bigvee}} \stackrel{VOUT}{\underset{RL}{\bigvee}}$	_	25	_	- ns
	Turn-on time	t _{on}		_	60	_	
	Fall time	t _f		_	20	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	95	_	
Total gate charge (gate-source plus gate-drain)		Qg		ı	58	ı	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		32	_	nC
Gate-drain ("miller") Charge		Q _{gd}			26	_	

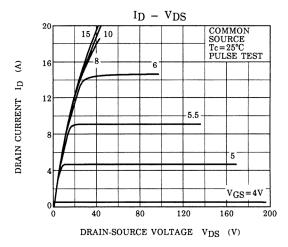
Source-Drain Ratings and Characteristics (Ta = 25°C)

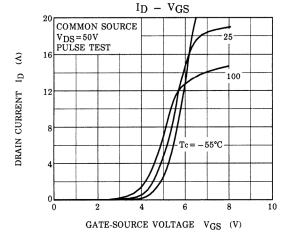
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	8	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	24	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs	_	1650	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	21	_	μC

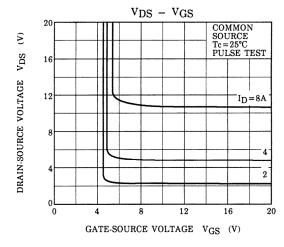
Marking

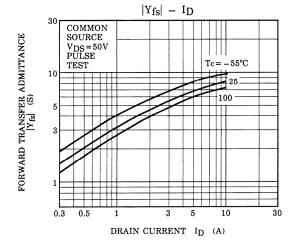


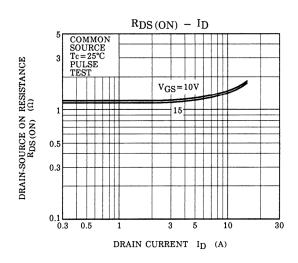


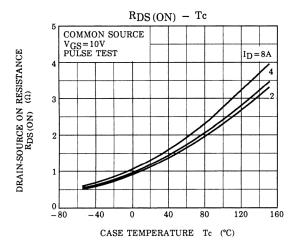


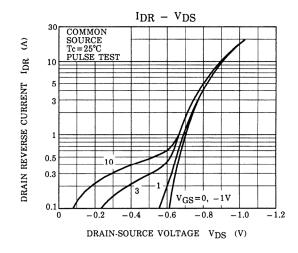


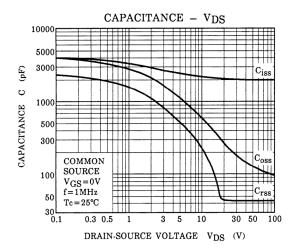


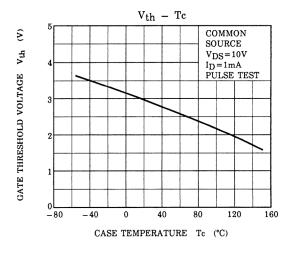


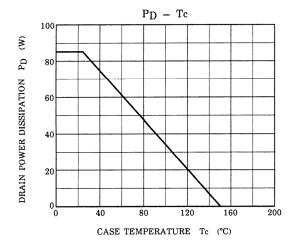


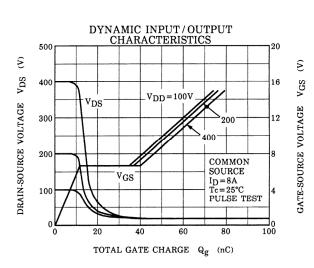




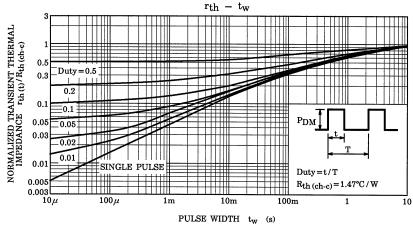


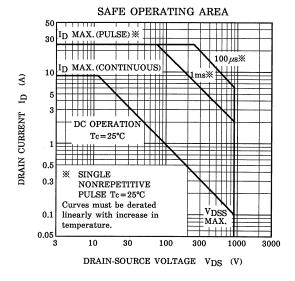


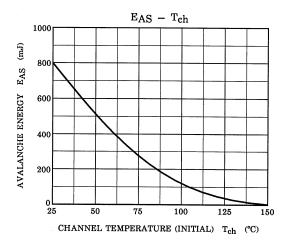


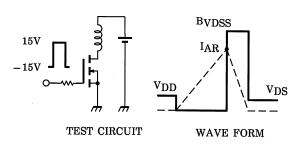


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$$R_G$$
 = 25 Ω
 V_{DD} = 90 V, L = 22.9 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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